



Click [here](#) for the 3D model.

| Dimensions | |
|------------|-----------------|
| Chip Size | 1206 |
| L | 3.2mm +/-0.2mm |
| W | 1.6mm +/-0.2mm |
| T | 1.6mm +/-0.20mm |
| B | 0.5mm +/-0.25mm |

| Packaging Specifications | |
|--------------------------|--------------------------|
| Packaging | T&R, 330mm, Plastic Tape |
| Packaging Quantity | 8000 |

| General Information | |
|---------------------|--|
| Series | ESD SMD Comm COG |
| Style | SMD Chip |
| Description | SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I |
| Features | Temperature Stable, Low ESR, Class I |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q200 | No |
| Component Weight | 36 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Specifications | |
|--|------------------------|
| Capacitance | 0.1 uF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Capacitance Tolerance | 5% |
| Voltage DC | 25 VDC |
| ESD Level per AEC-Q200 | 25,000 V ESD Level |
| Dielectric Withstanding Voltage | 62.5 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1kHz 1.0Vrms |
| Dissipation Factor | 0.1% 1 kHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 10 GOhms |

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.